
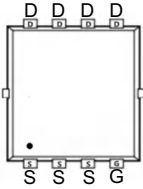
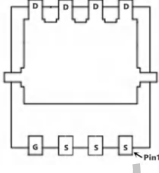

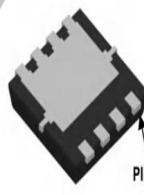
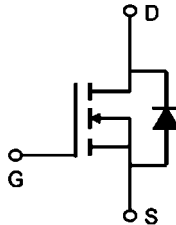


**TM150N04NF**

**N-Channel Enhancement Mosfet**

<p><b>General Description</b></p> <ul style="list-style-type: none"> <li>• Low <math>R_{DS(ON)}</math></li> <li>• RoHS and Halogen-Free Compliant</li> </ul> <p><b>Applications</b></p> <ul style="list-style-type: none"> <li>• Load switch</li> <li>• PWM</li> </ul>	<p><b>General Features</b></p> <p><math>V_{DS} = 40V</math> <math>I_D = 150A</math></p> <p><math>R_{DS(ON)} = 1.85 m\Omega (typ.) @ V_{GS} = 10V</math></p> <p>100% UIS Tested 100% <math>R_g</math> Tested</p>	
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NF:DFN5x6-8L

Marking: 150N04

**Absolute Maximum Ratings** ( $T_c = 25^\circ C$  unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	150	A
$I_{DM}$	Pulsed Drain Current	380	A
EAS	Single Pulse Avalanche Energy	500	mJ
$I_{AS}$	Avalanche Current	30	A
$P_D @ T_c = 25^\circ C$	Total Power Dissipation	96	W
$T_{STG}$	Storage Temperature Range	-55 to 175	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 175	$^\circ C$

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case	---	1.3	$^\circ C/W$

**TM150N04NF**

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**Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

Characteristics	Test Condition	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	BV <sub>DSS</sub>	40	-	-	V
Drain-Source Leakage Current	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V	I <sub>DSS</sub>	-	-	1	μA
Gate Leakage Current	V <sub>GS</sub> = ± 20 V, V <sub>DS</sub> = 0 V	I <sub>GSS</sub>	-	-	±100	nA
Gate-Source Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	V <sub>GS(th)</sub>	1.2	1.6	2.0	V
Drain-Source On-State Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A	R <sub>DS(on)</sub>	-	1.85	2.7	mΩ
	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 15 A		-	2.5	3.5	mΩ
Input Capacitance	V <sub>DS</sub> =25 V, V <sub>GS</sub> =0V, f=1MHz	C <sub>iss</sub>	-	6680	-	pF
Output Capacitance		C <sub>oss</sub>	-	1256	-	pF
Reverse Transfer Capacitance		C <sub>rss</sub>	-	780	-	pF
Turn-on Delay Time	V <sub>DD</sub> =20 V, V <sub>GS</sub> =10 V, R <sub>G</sub> =3.7 Ω, I <sub>D</sub> =70A	t <sub>d(ON)</sub>	-	25	-	ns
Rise Time		t <sub>r</sub>	-	80	-	ns
Turn-Off Delay Time		t <sub>d(OFF)</sub>	-	85	-	ns
Fall Time		t <sub>f</sub>	-	42	-	ns
Total Gate Charge	V <sub>DS</sub> =20V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =70A	Q <sub>G</sub>	-	170	-	nC
Gate to Source Charge		Q <sub>GS</sub>	-	52	-	nC
Gate to Drain Charge		Q <sub>GD</sub>	-	70	-	nC

Characteristics	Test Condition	Symbo	Min.	Typ.	Max.	Unit
Maximun Body-Diode Continuous Current		I <sub>S</sub>	-	-	150	A
Drain-Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =20A, T <sub>J</sub> =25°C	V <sub>SD</sub>	-	-	1.2	V
Reverse Recovery Time	T <sub>J</sub> = 25°C, I <sub>F</sub> = 40A di / dt = 100 A/μs	trr	-	31	-	ns
Reverse Recovery Charge		Qrr	-	27	-	nC



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N-Channel Enhancement Mosfet

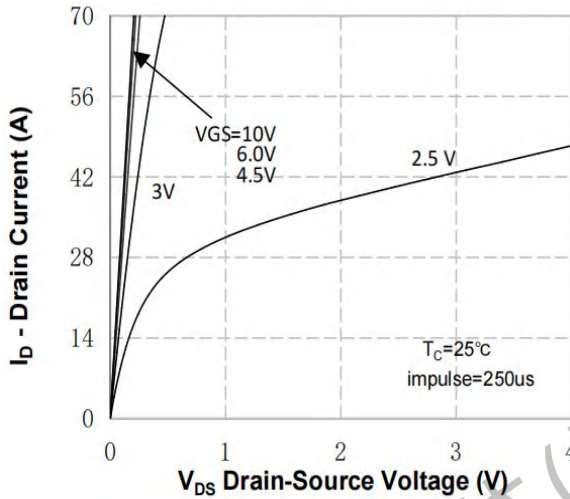


Figure 1. On-Region Characteristics

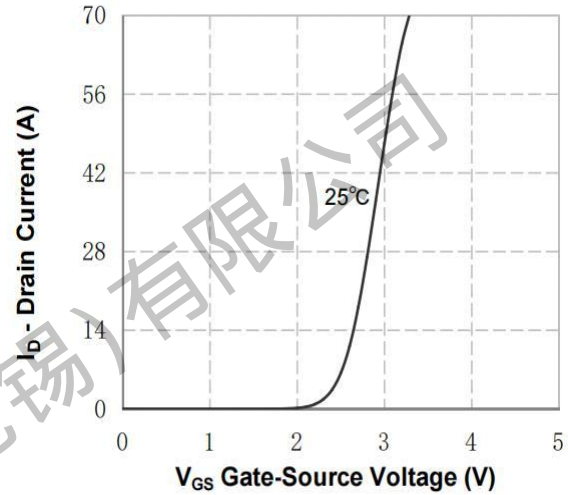


Figure 2. Transfer Characteristics

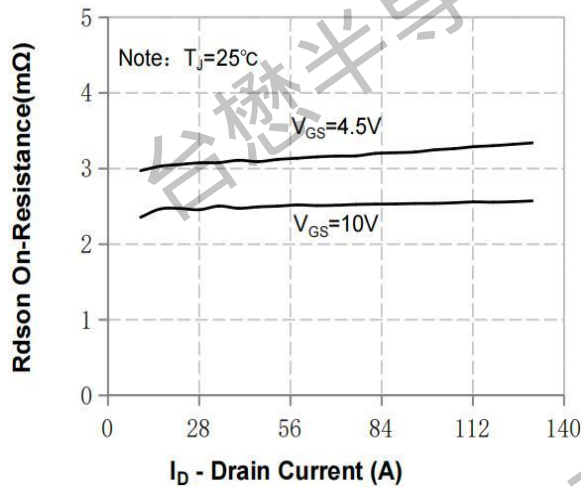


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

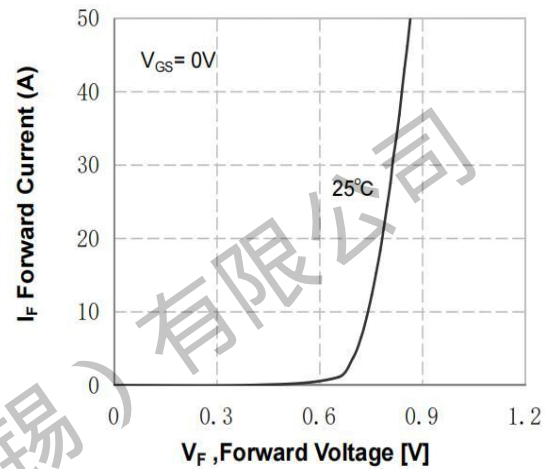


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

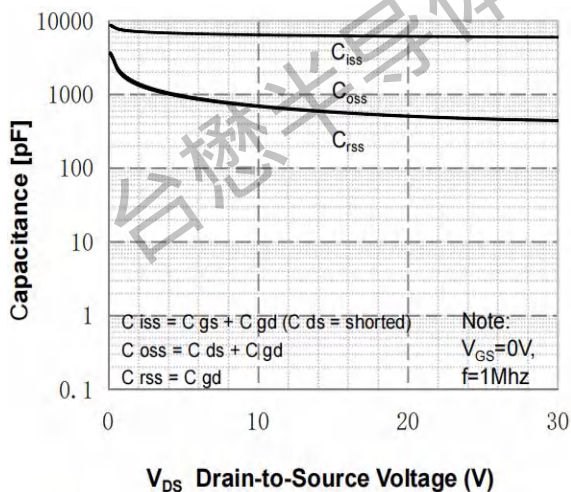


Figure 5. Capacitance Characteristics

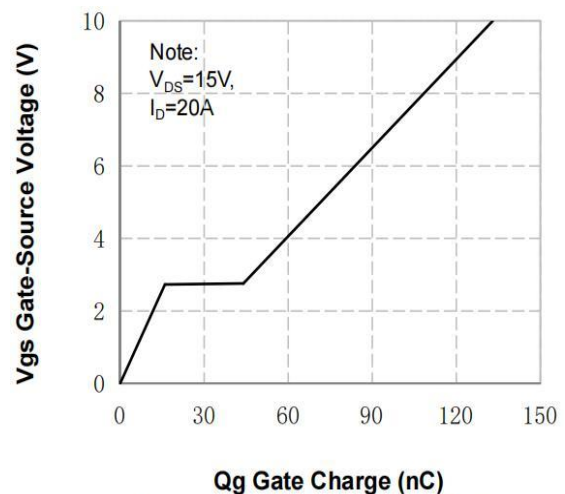
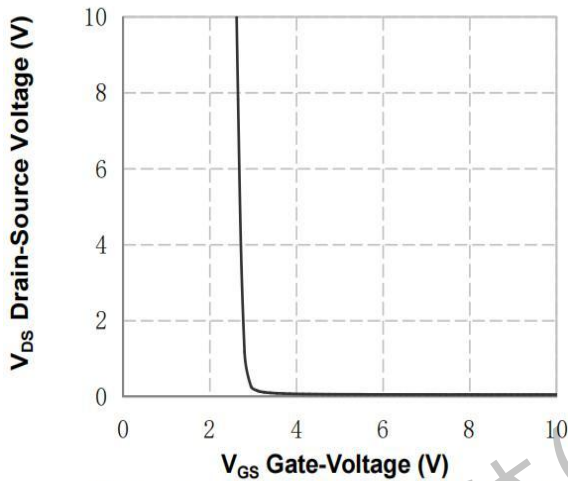


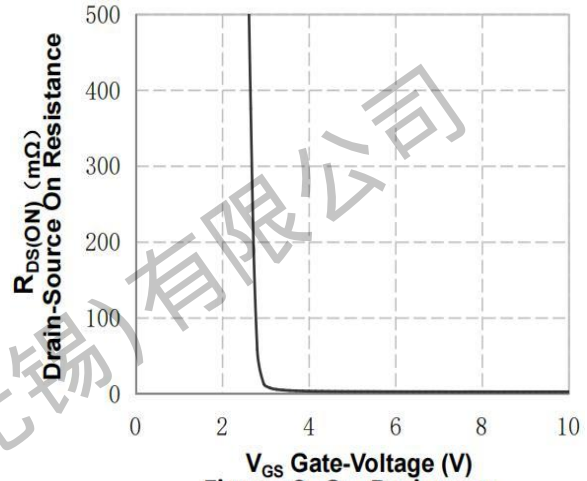
Figure 6. Gate Charge Characteristics

**TM150N04NF**

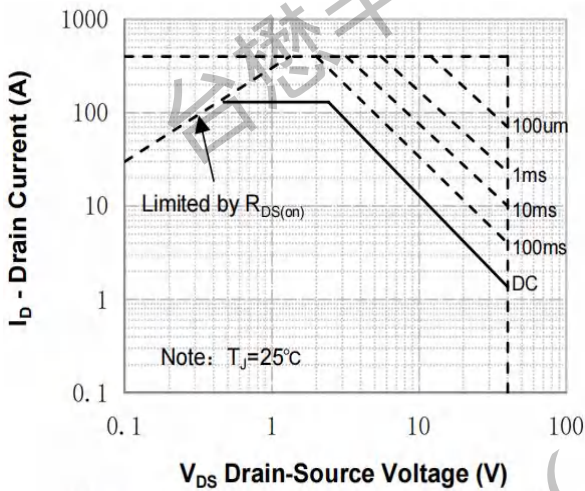
**N-Channel Enhancement Mosfet**



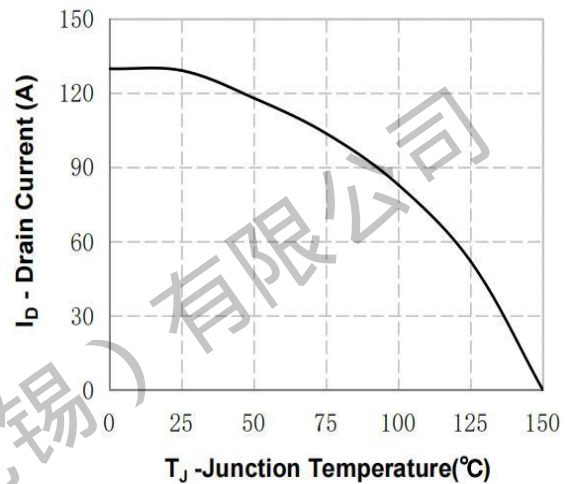
**Figure 7. Vds Drain-Source Voltage vs Gate Voltage**



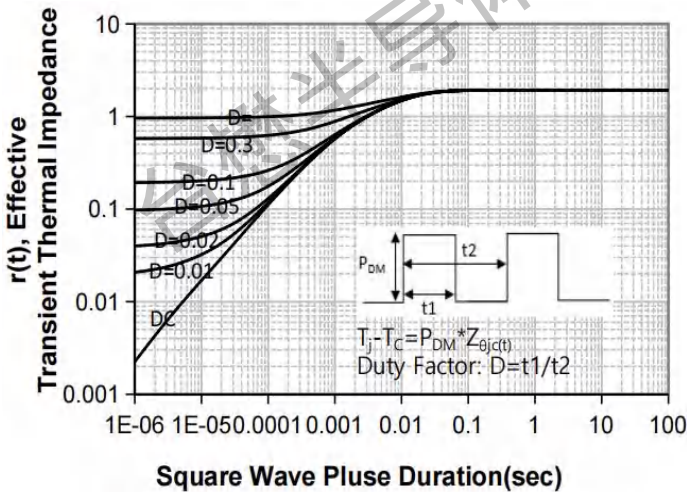
**Figure 8. On-Resistance vs Gate Voltage**



**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Continuous Drain Current vs Case Temperature**

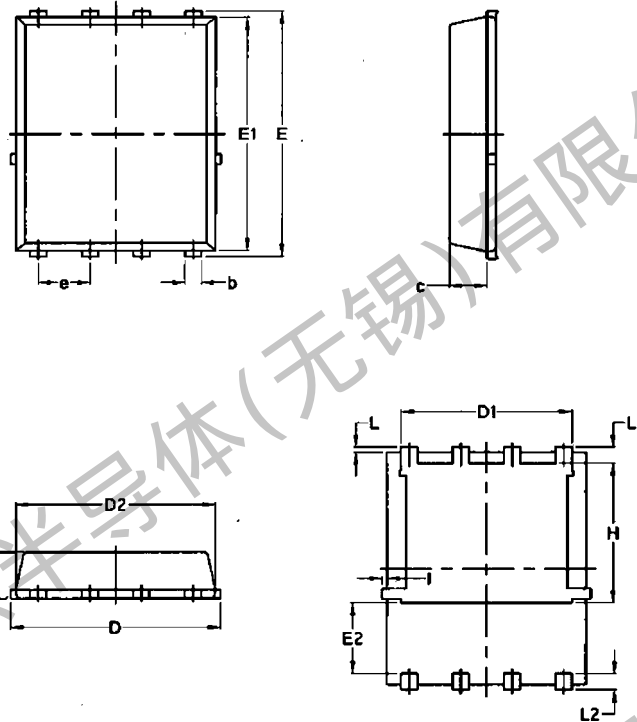


**Figure 11. Transient Thermal Response Curve**

TM150N04NF

N-Channel Enhancement Mosfet

Package Mechanical Data:DFN5x6-8L

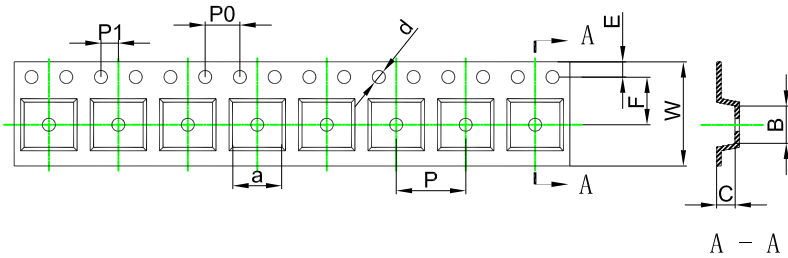


Symbol	Common			
	mm		Inch	
	Min	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
l	/	0.18	/	0.0070

**TM150N04NF**

**N-Channel Enhancement Mosfet**

**PDFN5x6-8L Embossed Carrier Tape**



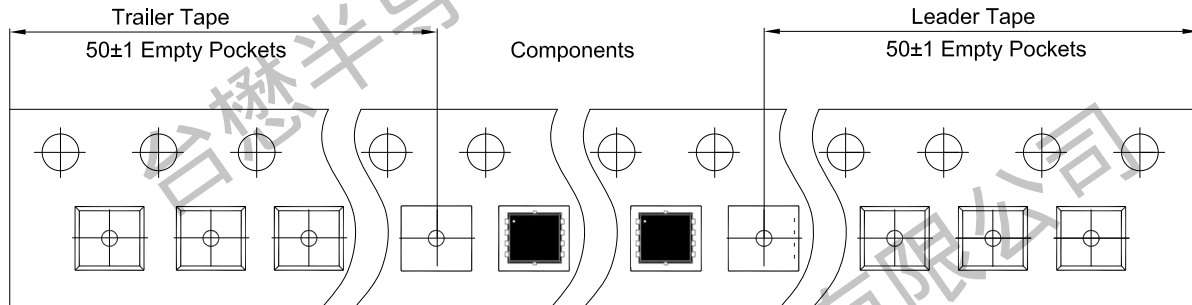
**Packaging Description:**

SOP-8L parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 2,500 units per 13" or 33cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).

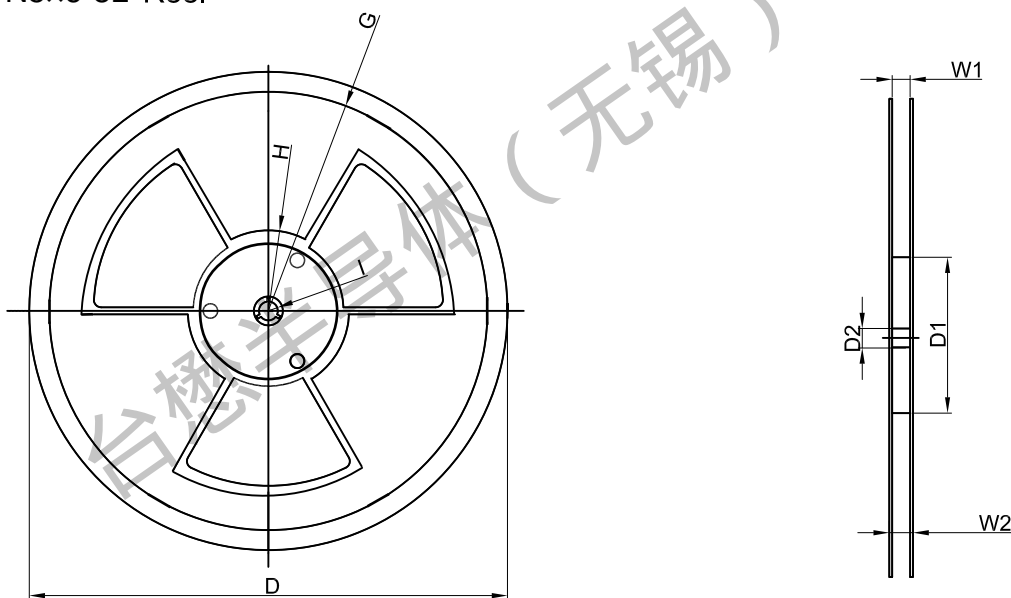
ALL DIM IN mm

Dimensions are in millimeter										
Pkg type	a	B	C	d	E	F	P0	P	P1	W
PDFN5x6-8L	6.40	5.40	2.10	Ø1.50	1.75	5.50	4.00	8.00	2.00	12.00

**PDFN5x6-8L Tape Leader and Trailer**



**PDFN5x6-8L Reel**



Dimensions are in millimeter								
Reel Option	D	D1	D2	G	H	I	W1	W2
13" Dia	Ø330.00	100.00	13.00	R135.00	R55.00	R6.50	12.00	14.00

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
5,000 pcs	13 inch	10,000 pcs	370×355×52	50,000 pcs	400×360×368	



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Revision history:

Date	Rev	Description	Page
2023.07.28	23.07	Original	